

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

- 1. (Previously Presented)** A substrate processing method including:
a first step of injecting droplets formed by mixing an alkaline solution and gas to a surface of a substrate; and
a second step of injecting droplets formed by mixing an acid solution and gas to the surface of said substrate after said first step, wherein
said alkaline solution and said acid solution are at an ordinary temperature.
- 2. (Original)** The substrate processing method according to claim 1, wherein
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.
- 3. (Original)** The substrate processing method according to claim 2, wherein
said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.
- 4. (Previously Presented)** A substrate processing method including:
a first step of supplying an alkaline solution imparted with megasonic vibrations to a surface of a substrate; and
a second step of supplying an acid solution to the surface of said substrate after said first step, wherein
said alkaline solution and said acid solution are at an ordinary temperature.
- 5. (Original)** The substrate processing method according to claim 4, wherein
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

6. (Original) The substrate processing method according to claim 5, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

7. (Previously Presented) A substrate processing method including:
a first step of supplying an alkaline solution to a surface of a substrate;
a second step of supplying an acid solution to the surface of said substrate after said first step; and
a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein
at least either supply of said acid solution in said second step or supply of said alkaline solution in said third step comprises injection of droplets formed by mixing said solution with gas.

8. (Original) The substrate processing method according to claim 7, wherein only supply of said alkaline solution in said first step and said third step is injection of droplets formed by mixing said alkaline solution with gas.

9. (Previously Presented) The substrate processing method according to claim 8, wherein
said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

10. (Original) The substrate processing method according to claim 9, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

11. (Previously Presented) A substrate processing method including:
a first step of supplying an alkaline solution to a surface of a substrate;
a second step of supplying an acid solution to the surface of said substrate after said first step; and

a third step of supplying said alkaline solution to the surface of said substrate after said second step, wherein

at least either supply of said acid solution in said second step or supply of said alkaline solution in said third step comprising supplying of said solution subjected to megasonic vibrations.

12. (Previously Presented) The substrate processing method according to claim 11, wherein

only the supply of said alkaline solution in said first step and said third step is performed with said alkaline solution subjected to megasonic vibrations.

13. (Previously Presented) The substrate processing method according to claim 12, wherein

said alkaline solution is a mixed solution containing ammonia water and hydrogen peroxide water.

14. (Original) The substrate processing method according to claim 13, wherein said acid solution is a mixed solution containing hydrochloric acid and hydrofluoric acid.

15. - 18. (Canceled)

19. (Previously Presented) A substrate processing method according to claim 1, wherein

said alkaline solution has a pH value of at least 11 and less than 13.

20. (Previously Presented) The substrate processing method according to claim 4, wherein

said alkaline solution has a pH value of at least 11 and less than 13.

- 21. (Previously Presented)** The substrate processing method according to claim 7, said alkaline solution and said acid solution being at an ordinary temperature.
- 22. (Previously Presented)** The substrate processing method according to claim 21, wherein
said alkaline solution has a pH value of at least 11 and less than 13.
- 23. (Previously Presented)** The substrate processing method according to claim 11,
said alkaline solution and said acid solution being at an ordinary temperature.
- 24. (Previously Presented)** The substrate processing method according to claim 23, wherein
said alkaline solution has a pH value of at least 11 and less than 13.
- 25. (New)** The substrate processing method according to claim 1, wherein droplets of said alkaline solution are injected from a nozzle to said surface of said substrate in said first step.
- 26. (New)** The substrate processing method according to claim 4, wherein droplets of said alkaline solution are injected from a nozzle to said surface of said substrate in said first step.
- 27. (New)** The substrate processing method according to claim 7, wherein droplets of said alkaline solution are injected from a nozzle to said surface of said substrate in said first step.
- 28. (New)** The substrate processing method according to claim 11, wherein droplets of said alkaline solution are injected from a nozzle to said surface of said substrate in said first step.